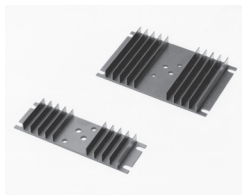


EXTRUDED HEAT SINKS FOR POWER SEMICONDUCTORS



621 & 623 SERIES

LOW-PROFILE HEAT SINKS FOR ALL METAL-CASE  
POWER SEMICONDUCTORS

TO-3

A general purpose yet efficient heat dissipator for TO-3 and virtually all other styles of metal case power semiconductor package types, the **621 and 623 Series** low-profile flat back heat sinks find a wide variety of applications. The central channel between fins measures 1.300 in. (33.0) (min.) in width, accommodating many types of packages. Mounting hole pattern “A” is pre-drilled for the standard TO-3 package.

Standard P/N	Footprint Dimensions in. (mm)	Height in. (mm)	Mounting Hole Pattern	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
621A	4.750 (120.6) x 1.500 (38.1)	0.461 (11.7)	(1) TO-3	75°C @ 15W	2.0°C/W @ 250 LFM	0.1000 (45.36)
621K	4.750 (120.6) x 1.500 (38.1)	0.461 (11.7)	None	75°C @ 15W	2.0°C/W @ 250 LFM	0.1000 (45.36)
623A	4.750 (120.6) x 3.000 (76.2)	0.461 (11.7)	(1) TO-3	52°C @ 15W	1.5°C/W @ 250 LFM	0.2100 (95.26)
623K	4.750 (120.6) x 3.000 (76.2)	0.461 (11.7)	None	52°C @ 15W	1.5°C/W @ 250 LFM	0.2100 (95.26)

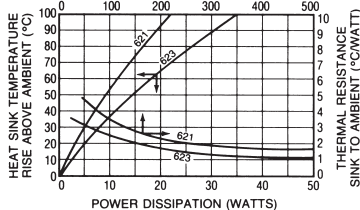
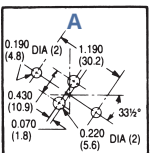
Material: Aluminum Alloy, Black Anodized.

MECHANICAL DIMENSIONS

(EXTRUSION PROFILE 1327)

NATURAL AND FORCED  
CONVECTION CHARACTERISTICS

SEMICONDUCTOR  
MOUNTING HOLES



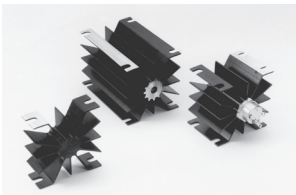
Dimensions: in. (mm)

COMPACT HEAT SINKS FOR DUAL  
STUD-MOUNTED SEMICONDUCTOR CASES

301, 302, &  
303 SERIES

Stud-Mount

The large fin area in minimum total volume provided by the radial design of the **301/302/303 Series** offers maximum heat transfer efficiency in natural convection. All types are available with one tapped mounting hole for rectifiers and other stud-mounting semiconductor; the 302 and 303 Series offer maximum cost savings with dual mounting locations (“MM” and “NN” mounting hole patterns) for two stud-mount devices.



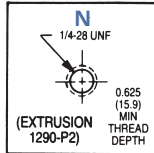
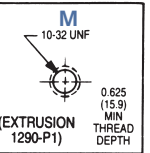
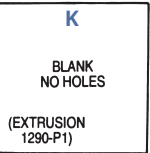
Standard P/N	Outline Dimensions in. (mm)	Length “A” in. (mm)	Mounting Hole(s) Pattern and Number	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
301K	2.000 (50.8) x 2.000 (50.8)	0.750 (19.1)	None	70°C @ 15W	2.5°C/W @ 250 LFM	0.0580 (26.31)
301M	2.000 (50.8) x 2.000 (50.8)	0.750 (19.1)	(1) 10-32UNF, 0.625 in. thread depth	70°C @ 15W	2.5°C/W @ 250 LFM	0.0580 (26.31)
301N	2.000 (50.8) x 2.000 (50.8)	0.750 (19.1)	(1) 1/4 -28UNF, 0.625 in. thread depth	70°C @ 15W	2.5°C/W @ 250 LFM	0.0580 (26.31)
302M	2.000 (50.8) x 2.000 (50.8)	1.500 (38.1)	(1) 10-32UNF, 0.625 in. thread depth	50°C @ 15W	1.8°C/W @ 250 LFM	0.1330 (60.33)
302MM	2.000 (50.8) x 2.000 (50.8)	1.500 (38.1)	(2) 10-32UNF, 0.625 in. thread depth	50°C @ 15W	1.8°C/W @ 250 LFM	0.1330 (60.33)
302N	2.000 (50.8) x 2.000 (50.8)	1.500 (38.1)	(1) 1/4 -28UNF, 0.625 in. thread depth	50°C @ 15W	1.8°C/W @ 250 LFM	0.1330 (60.33)
302NN	2.000 (50.8) x 2.000 (50.8)	1.500 (38.1)	(2) 1/4 -28UNF, 0.625 in. thread depth	50°C @ 15W	1.8°C/W @ 250 LFM	0.1330 (60.33)
303M	2.000 (50.8) x 2.000 (50.8)	3.000 (76.2)	(1) 10-32UNF, 0.625 in. thread depth	37°C @ 15W	1.3°C/W @ 250 LFM	0.2680 (121.56)
303MM	2.000 (50.8) x 2.000 (50.8)	3.000 (76.2)	(2) 10-32UNF, 0.625 in. thread depth	37°C @ 15W	1.3°C/W @ 250 LFM	0.2680 (121.56)
303N	2.000 (50.8) x 2.000 (50.8)	3.000 (76.2)	(1) 1/4 -28UNF, 0.625 in. thread depth	37°C @ 15W	1.3°C/W @ 250 LFM	0.2680 (121.56)
303NN	2.000 (50.8) x 2.000 (50.8)	3.000 (76.2)	(2) 1/4 -28UNF, 0.625 in. thread depth	37°C @ 15W	1.3°C/W @ 250 LFM	0.2680 (121.56)

Material: Aluminum Alloy, Black Anodized.

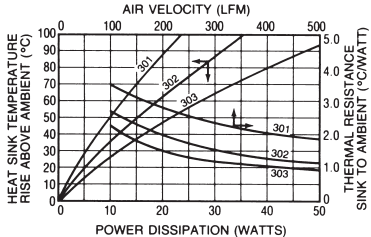
MECHANICAL DIMENSIONS

NOTE: CROSS-HATCHED AREAS FREE OF ANODIZE.

SEMICONDUCTOR MOUNTING HOLES



NATURAL AND FORCED  
CONVECTION CHARACTERISTICS



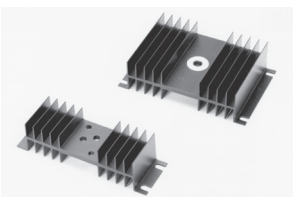
302 AND 303 SERIES

301 SERIES

Dimensions: in. (mm)

DOUBLE-SURFACE HEAT SINKS  
FOR TO-3 CASE STYLES

401 & 403 SERIES



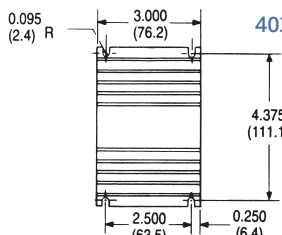
TO-3; Stud-Mount

With fins oriented vertically in cabinet sidewall applications, **401 and 403 Series** heat sinks are recommended for critical space applications where maximum heat dissipation is required for high-power TO-3 case styles. Forced convection performance is also exemplary with these double surface fin types. Semiconductor mounting hole style “F” offers a single centered 0.270 in. (6.9)-diameter mounting hole (with a 0.750 in. (19.1)-diameter area free of anodize) for mounting stud-type diodes and rectifiers. Hole pattern “V” available upon request.

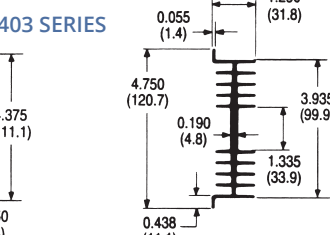
Standard P/N	Width in. (mm)	Overall Dimensions in. (mm)	Height in. (mm)	Semiconductor Mounting Hole Pattern	Thermal Performance at Typical Load		Weight lbs. (grams)
					Natural Convection	Forced Convection	
401A	4.750 (120.7)	1.500 (38.1)	1.250 (31.8)	(1) TO-3	80°C @ 30W	1.5°C/W @ 250 LFM	0.1500 (68.04)
401F	4.750 (120.7)	1.500 (38.1)	1.250 (31.8)	0.270 in. (6.9)-Dia Hole	80°C @ 30W	1.5°C/W @ 250 LFM	0.1500 (68.04)
401K	4.750 (120.7)	1.500 (38.1)	1.250 (31.8)	None	80°C @ 30W	1.5°C/W @ 250 LFM	0.1500 (68.04)
403A	4.750 (120.7)	3.000 (76.2)	1.250 (31.8)	(1) TO-3	55°C @ 30W	0.9°C/W @ 250 LFM	0.3500 (158.76)
403F	4.750 (120.7)	3.000 (76.2)	1.250 (31.8)	0.270 in. (6.9)-Dia Hole	55°C @ 30W	0.9°C/W @ 250 LFM	0.3500 (158.76)
403K	4.750 (120.7)	3.000 (76.2)	1.250 (31.8)	None	55°C @ 30W	0.9°C/W @ 250 LFM	0.3500 (158.76)

Material: Aluminum Alloy, Black Anodized.

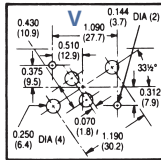
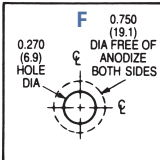
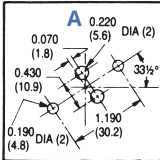
MECHANICAL DIMENSIONS



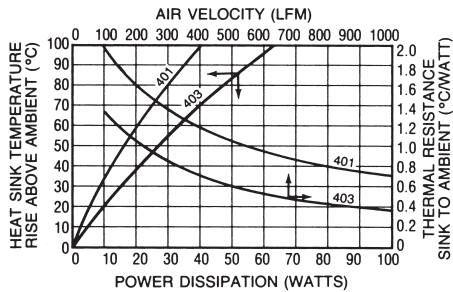
Dimensions: in. (mm)



SEMICONDUCTOR MOUNTING HOLES



NATURAL AND FORCED  
CONVECTION CHARACTERISTICS



(EXTRUSION PROFILE 1024)

441 SERIES

HIGH-PERFORMANCE NATURAL CONVECTION HEAT  
SINKS FOR RECTIFIERS AND DIODES

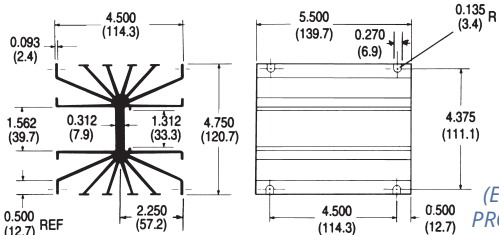
Stud-Mount

Designed for vertical mounting within a power supply enclosure or equipment cabinet without forced airflow available. This Wakefield-Vette **441 Series** heat sink will dissipate up to 100 watts efficiently in natural convection with a maximum 55°C heat sink temperature rise above ambient. When applied in a forced convection environment, the 441K Type will achieve thermal resistance of 0.18°C/W (sink to ambient) at 1000 LFM. Supplied with no pre-drilled device mounting hole pattern.

Standard P/N	Nominal Dimensions			Semiconductor Mounting Hole Pattern	Thermal Performance at Typical Load		Weight lbs. (grams)
	Width in. (mm)	Length in. (mm)	Height in. (mm)		Natural Convection	Forced Convection	
441K	4.750 (120.7)	5.500 (139.7)	4.500 (114.3)	None	34°C @ 50W 47°C @ 80W	0.30°C/W @ 250 LFM 0.19°C/W @ 600 LFM	1.9700 (893.59)

Material: Aluminum Alloy, Black Anodized.

MECHANICAL DIMENSIONS



Dimensions: in. (mm)

SEMICONDUCTOR MOUNTING HOLE



NATURAL AND FORCED  
CONVECTION CHARACTERISTICS

